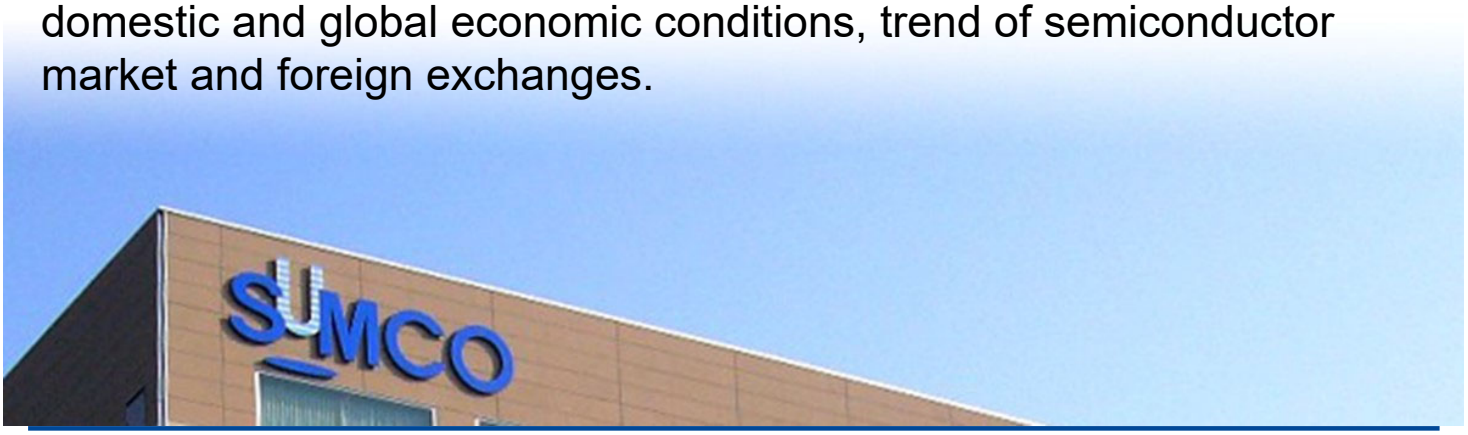
Results for Fiscal Year 2024 (Ended December 31, 2024)

February 7, 2025
SUMCO Corporation
（Code：3436）
（LEI：353800SUSRUOM0V6KU92）

Notes Regarding the Forecasts

This material is prepared for the purpose of continuous disclosure to general shareholders and investors and will not constitute an offer or solicitation of securities of the Company in any states or jurisdictions.

The estimate, expectation, forecast and other future information is prepared based on the information which is available for the Company as of today and on certain assumptions and qualifications (which includes our subjective judgment) and the actual financial performance or result may be substantially different from such future information contained in the material due to risk factors including domestic and global economic conditions, trend of semiconductor market and foreign exchanges.



Contents

- Summary and Market Environment
- FY2024 Consolidated Business Result
  - Summary of Consolidated Business Result
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  - Consolidated Balance Sheet and Consolidated Cash-Flow
- 1Q-2025 Consolidated Business Forecast
  - Consolidated Business Forecast
  - Analysis of Changes in Operating Profit
- Reference Materials



Summary and Market Environment

Mayuki Hashimoto

Representative Director,
CEO & Chairman of the Board

1-1. Summary

4Q-2024 Consolidated Business Result

(Billions of Yen)

	4Q-2024 Forecast	4Q-2024 Actual	Change
Net Sales	97.0	100.0	+3.0
Operating Profit	5.0	7.0	+2.0
Ordinary Profit	7.0	11.4	+4.4
Profit (Note)	4.0	3.6	(0.4)
Exchange Rate (Yen/US$)	150.0	149.2	(0.8)

1Q-2025 Consolidated Business Forecast

(Billions of Yen)

	4Q-2024 Actual	1Q-2025 Forecast	Change
Net Sales	100.0	102.0	+2.0
Operating Profit	7.0	4.5	(2.5)
Ordinary Profit	11.4	4.0	(7.4)
Profit (Note)	3.6	1.5	(2.1)
Exchange Rate (Yen/US$)	149.2	155.0	+5.8

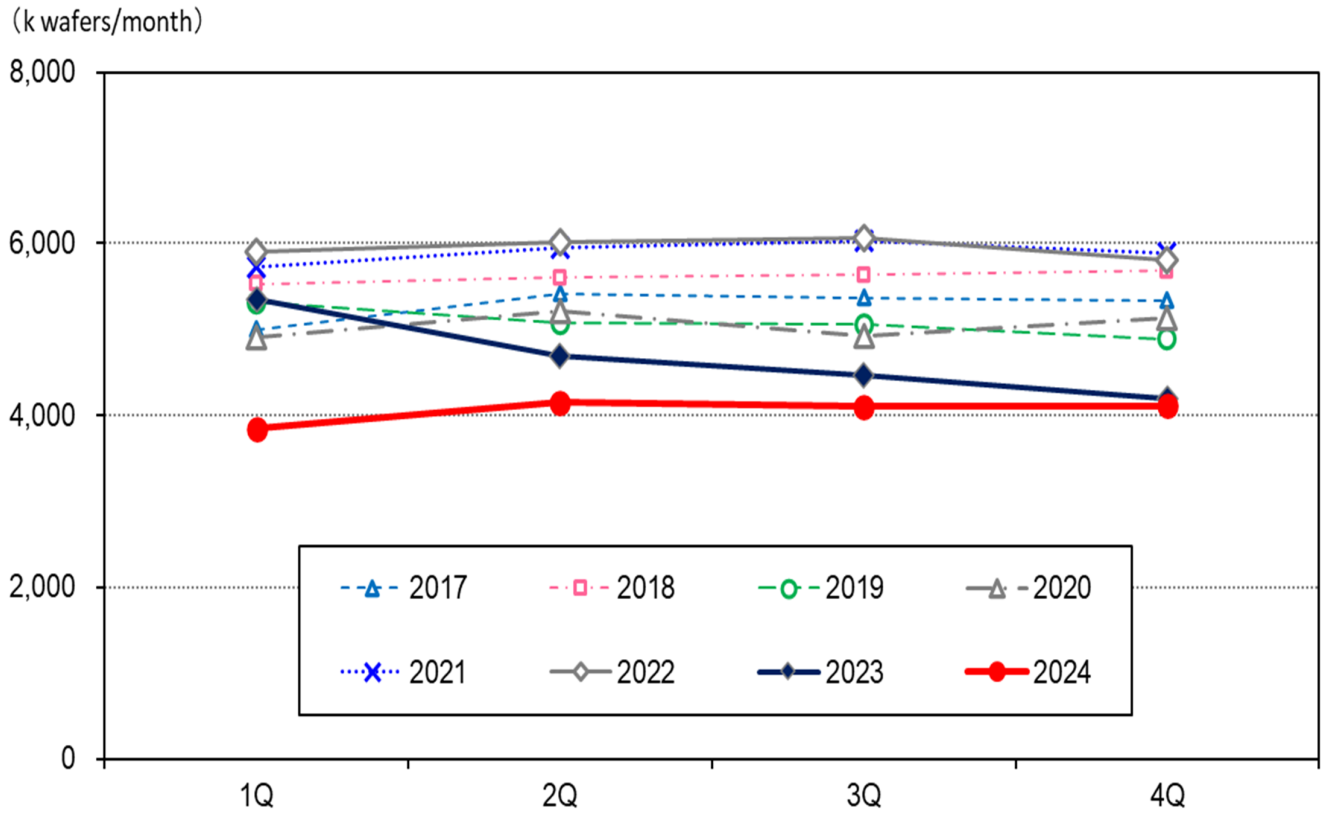
(Note) Profit attributable to owners of parent

1-2. Shareholder Return

		FY2019 (Dec-2019)	FY2020 (Dec-2020)	FY2021 (Dec-2021)	FY2022 (Dec-2022)	FY2023 (Dec-2023)	FY2024 (Dec-2024)
Dividends per share for common stocks (Yen)	Interim	25	18	17	36	42	15
	Year-end	10	9	24	45	13	6
	Total	35	27	41	81	55	21
Dividends payment (Billions of Yen)	Interim	7.3	5.2	4.9	12.6	14.7	5.2
	Year-end	2.9	2.6	8.4	15.7	4.5	2.1
	Total	10.2	7.8	13.3	28.3	19.2	7.3
Dividend ratio (%)	Total	31.0%	30.9%	30.2%	40.4%	31.0%	(*1) 39.7%
Share Buyback							
Amount (Billions of Yen)	Total	3.3	2.5	-	-	-	-
Ratio (%)	Total	10.0%	9.8%	-	-	-	-
Total Return Ratio (%)	Total	41.0%	40.7%	30.2%	40.4%	31.0%	39.7%

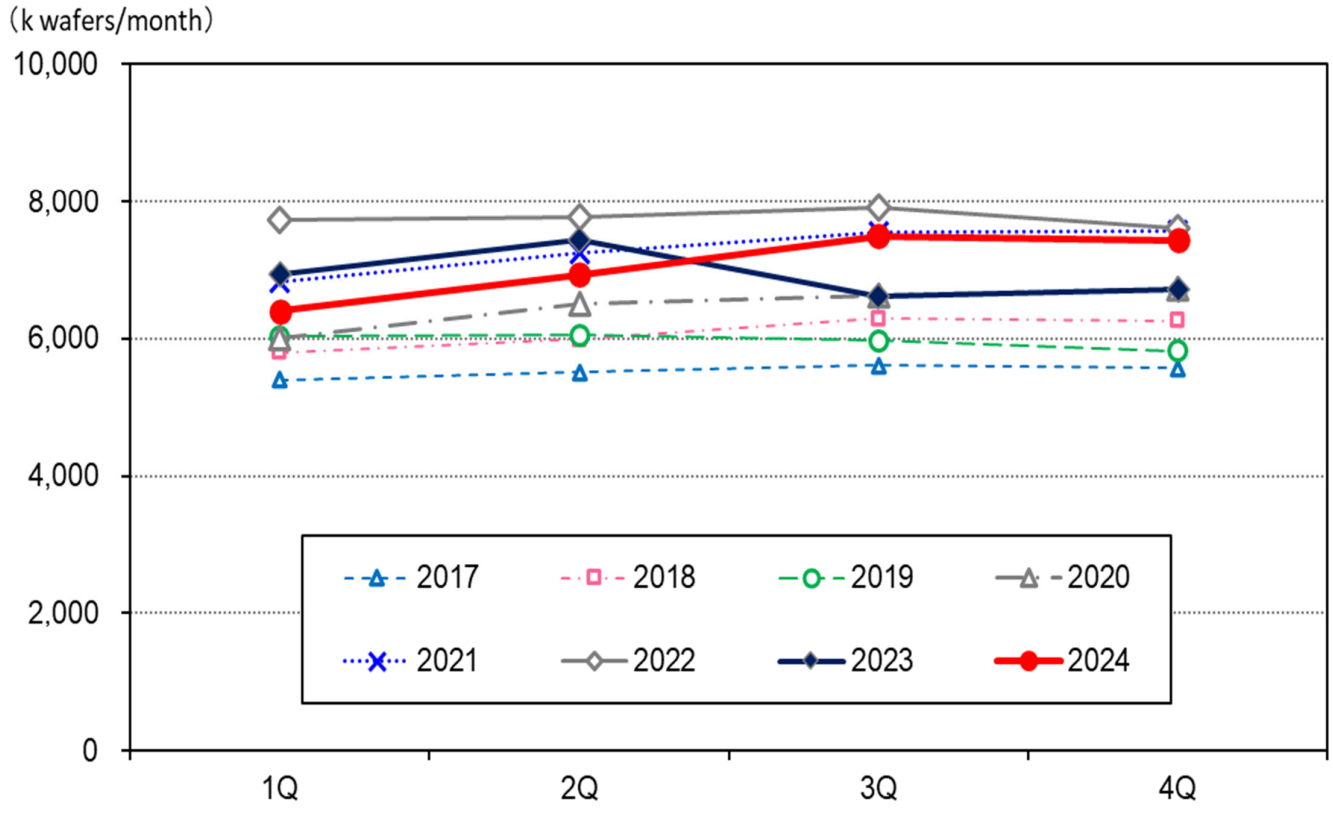
*1. Subsidy income after tax is excluded from dividends.

2-1. 200mm Wafer Trend



(Source: SUMCO's estimation)

2-2. 300mm Wafer Trend



(Source: SUMCO's estimation)

2-3. Market Environment

4Q-2024

- ✓ Volume - Shipments of 300 mm wafers were flat after a moderate recovery through 3Q.
  - Shipments remained slow for 200 mm and smaller wafers.
- ✓ Pricing - Long-term contract prices were honored for both 300 mm and 200 mm wafers.

1Q-2025 Forecast

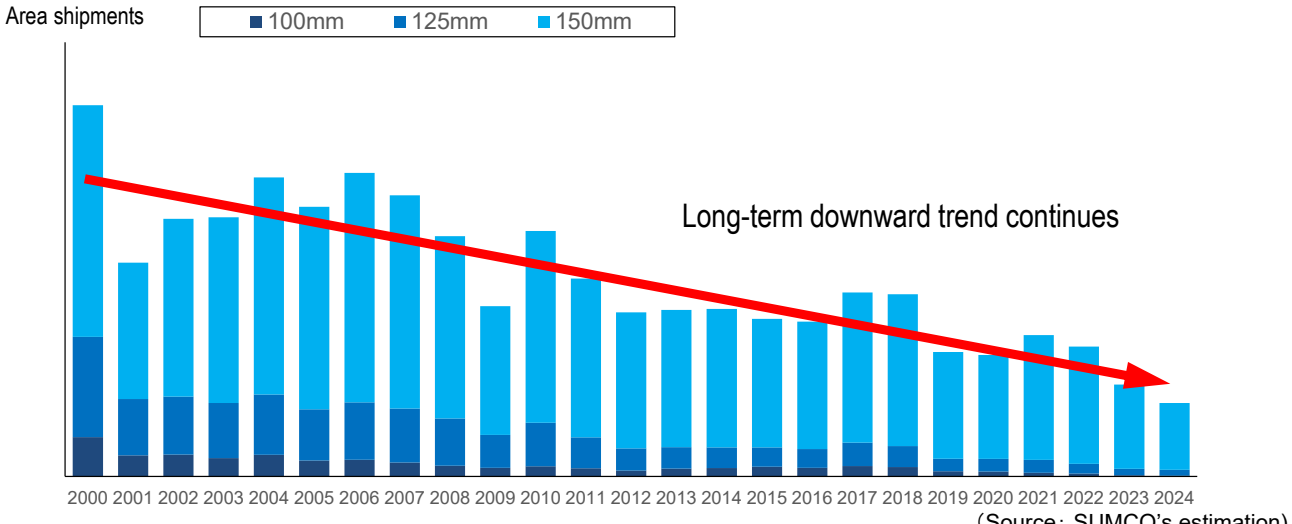
- ✓ Volume - 300 mm wafers for leading-edge products remain strong, but legacy products will take more time for customers wafer inventory drawdown due to sluggish recovery in demand, so that shipment recovery overall is expected to be gradual.
  - For 200 mm wafers, production adjustments at customer sites are likely to continue.
- ✓ Pricing - Long-term contract prices are being maintained for both 300 mm and 200 mm wafers, while spot prices vary widely by region and application.

Outlook

- ✓ The current bifurcated state of the semiconductor market is likely to continue, as demand remains strong for data center use driven by AI but is still slow to recover for applications other than AI.
- ✓ Silicon wafer demand is gradually recovering for 300 mm products. Shipments of wafers of 200 mm and smaller are expected to continue at a slow pace due to intensified competition from China and weak demand for consumer, industrial, and automotive uses.

2-4. Market Environment for Small-Diameter Wafers

Small-Diameter Wafer Market



(Source: SUMCO's estimation)

Demand Outlook for Small-Diameter Wafers

- ✓ Demand is currently sluggish, due to such factors as the reactionary fall from the pandemic and the slow recovery of demand for end products.
- ✓ Amid transition to larger wafer in semiconductor production, demand growth for wafers with a smaller diameter is not foreseen in the medium to long term.
- ✓ In China, as semiconductor manufacturing has been increasing, including with small wafers, local Chinese silicon wafer manufacturers are ramping up production and competition is likely to intensify.

2-5. Business Structural Reforms with Focus on Advanced Product

Amid accelerating semiconductor technology innovation, particularly for AI, we will focus management resources on boosting supply capacity for 300 mm leading-edge products and strive to further raise corporate value.

Reorganizing Production of Small Wafers

<Raising efficiency by consolidating production>

- ✓ Wafer production at the SUMCO TECHXIV Miyazaki Plant to be consolidated in other facilities toward greater efficiency and profitability
- ✓ Employees affected by the reorganization to be reassigned to 300 mm wafer operations

Miyazaki Plant Reorganization Plan

- ✓ Wafer production will end by the end of 2026, while monocrystalline manufacturing will continue.

200 mm	Transfer to plants in Nagasaki and Imari
150 mm	Transfer to plant in Indonesia
125 mm and others	Withdraw due to unprofitability
Monocrystalline	Continue to manufacture (wafer processing moved to other sites)

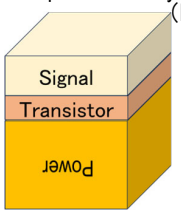
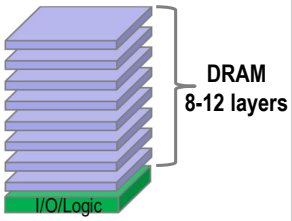
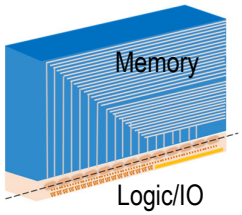
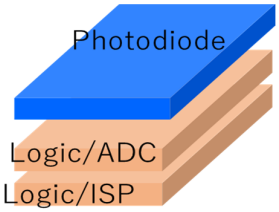
Posting of Losses Related to Business Structural Reforms

- ✓ With this reorganization, a total of ¥5.8 billion was posted as extraordinary losses for FY2024: ¥4.6 billion for impairment loss on non-current and ¥1.2billion for inventory write-down, etc.

3. Leading-Edge Devices using Wafer Bonding

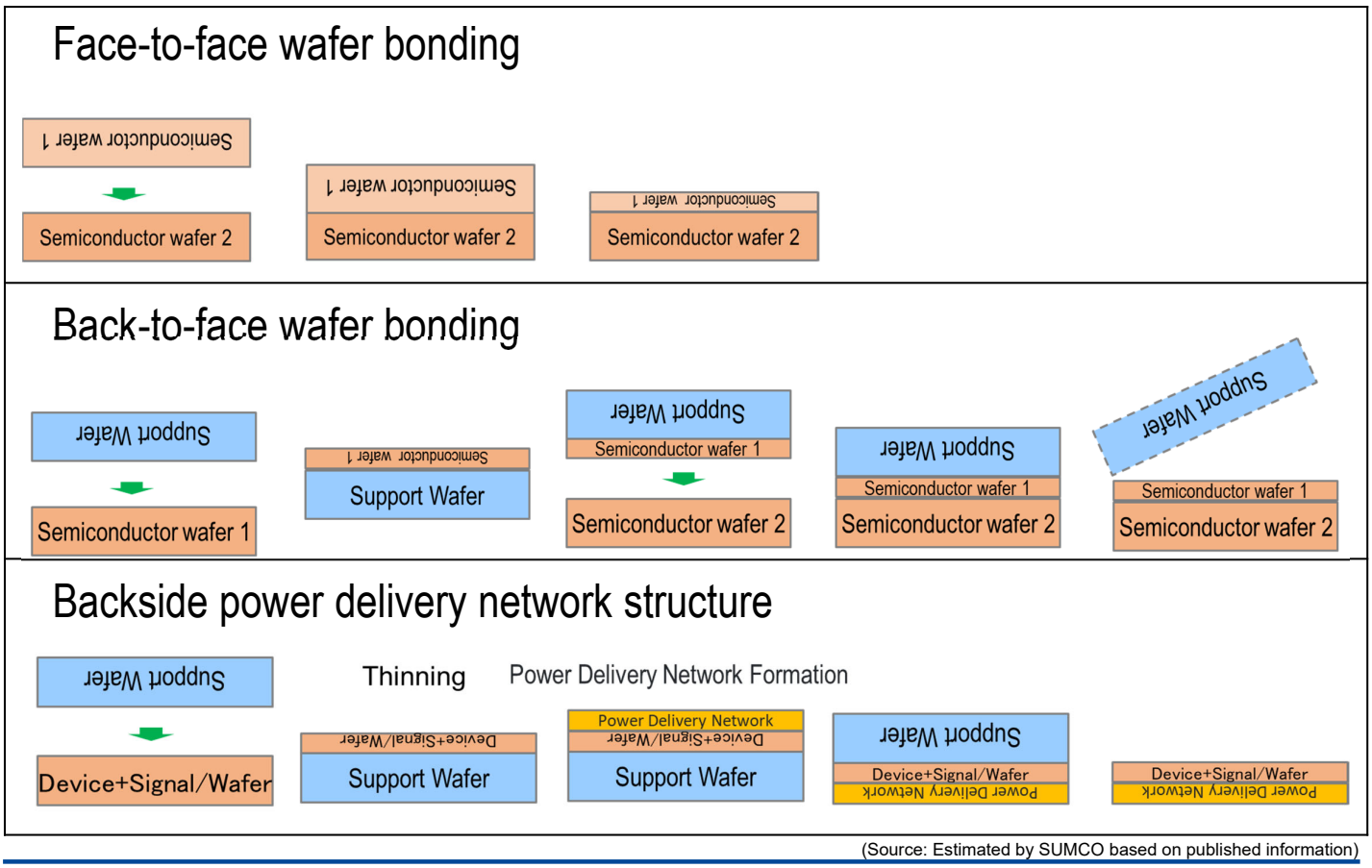
1. Structures of leading-edge devices using wafer bonding
2. Wafer bonding examples of leading-edge devices
3. DRAM bit demand forecast
4. 300 mm wafer demand forecast for DRAM
5. NAND bit demand forecast
6. 300 mm wafer demand forecast for NAND

3-1. Structures of leading-edge devices using wafer bonding

	Logic	DRAM	NAND	CIS
Structure	Backside power delivery network (BSPDN) 	HBM 		
Purpose	To avoid increasing interconnect resistance from scaling by separating power interconnect from the front side interconnect	DRAMs are stacked on top of control logic, realizing smaller chip area, larger capacity, and higher speed.	To realize shorter interconnect length and faster speed with a logic die at the bottom	To maximize photodiode area and improve video processing speed, with pixel and circuit sections put at the bottom
Wafers	2-3 wafers	the number of stacking DRAMs + 1 Logic die	2 wafers (Memory + Logic)	3 wafers (Photodiode + Logic + Logic)

(Source: Estimated by SUMCO based on published information)

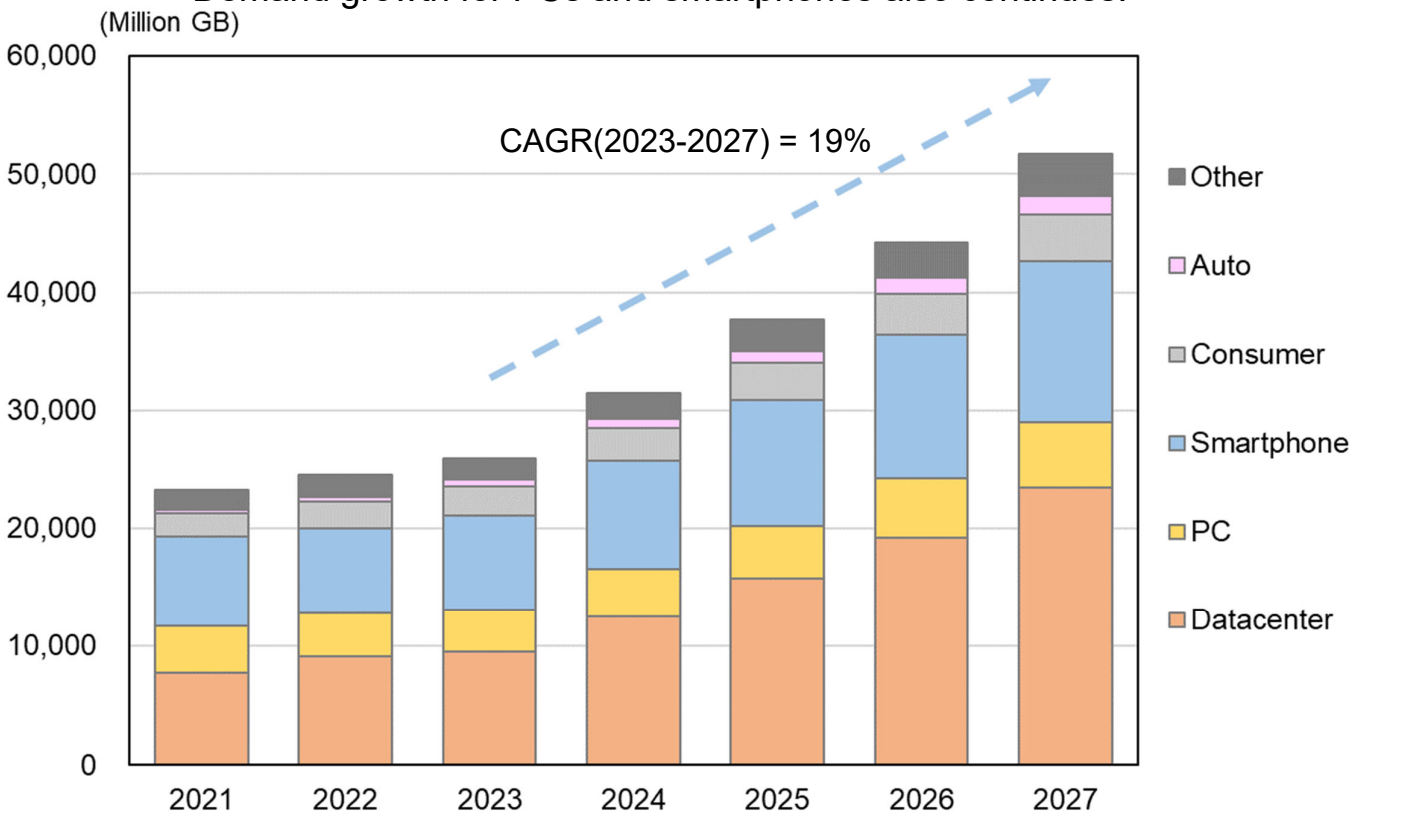
3-2. Wafer bonding examples of leading-edge devices



(Source: Estimated by SUMCO based on published information)

3-3. DRAM bit demand forecast

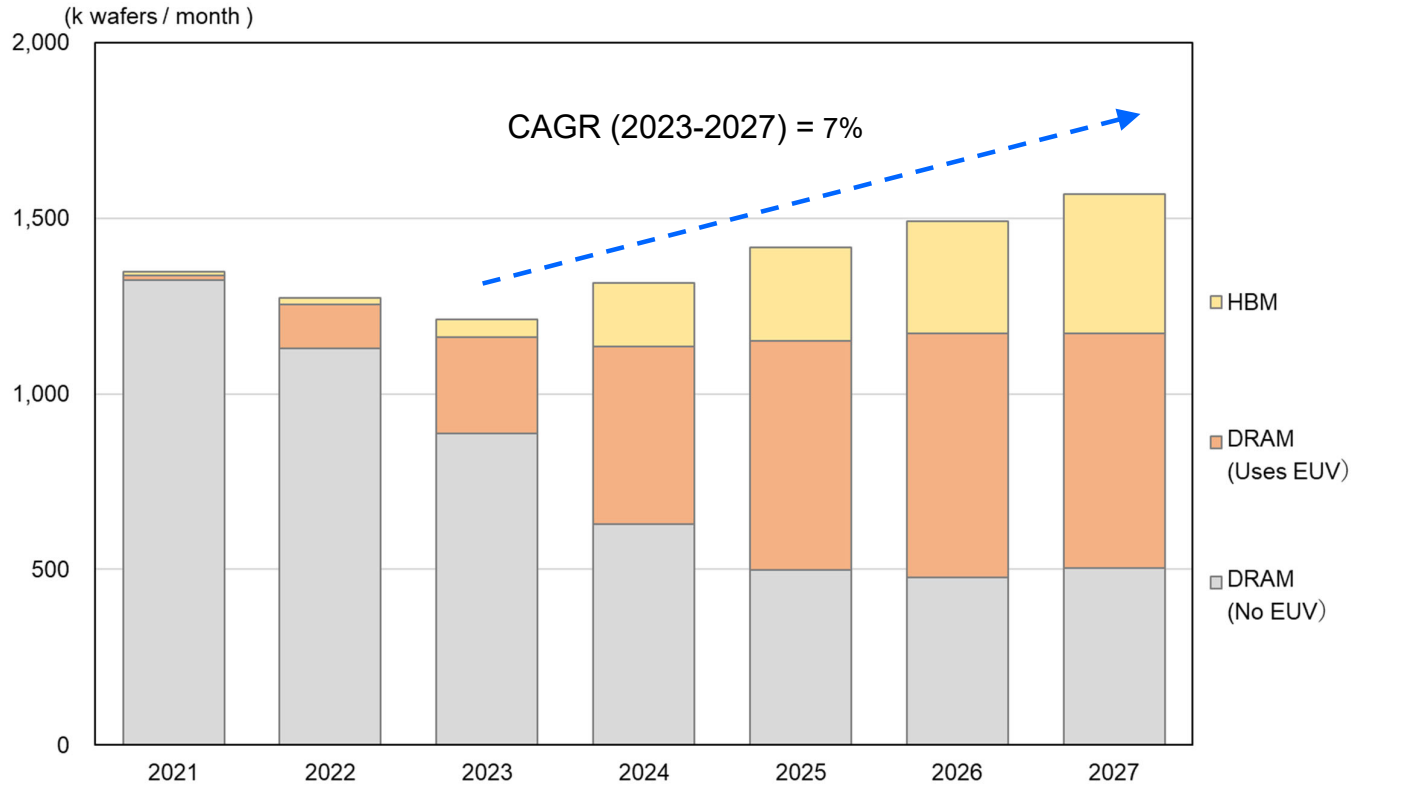
- ✓ Growth for data centers is strong.
- ✓ Demand growth for PCs and smartphones also continues.



(Source: Estimated by SUMCO based on data from multiple market research firms)

3-4. 300 mm wafer demand forecast for DRAM

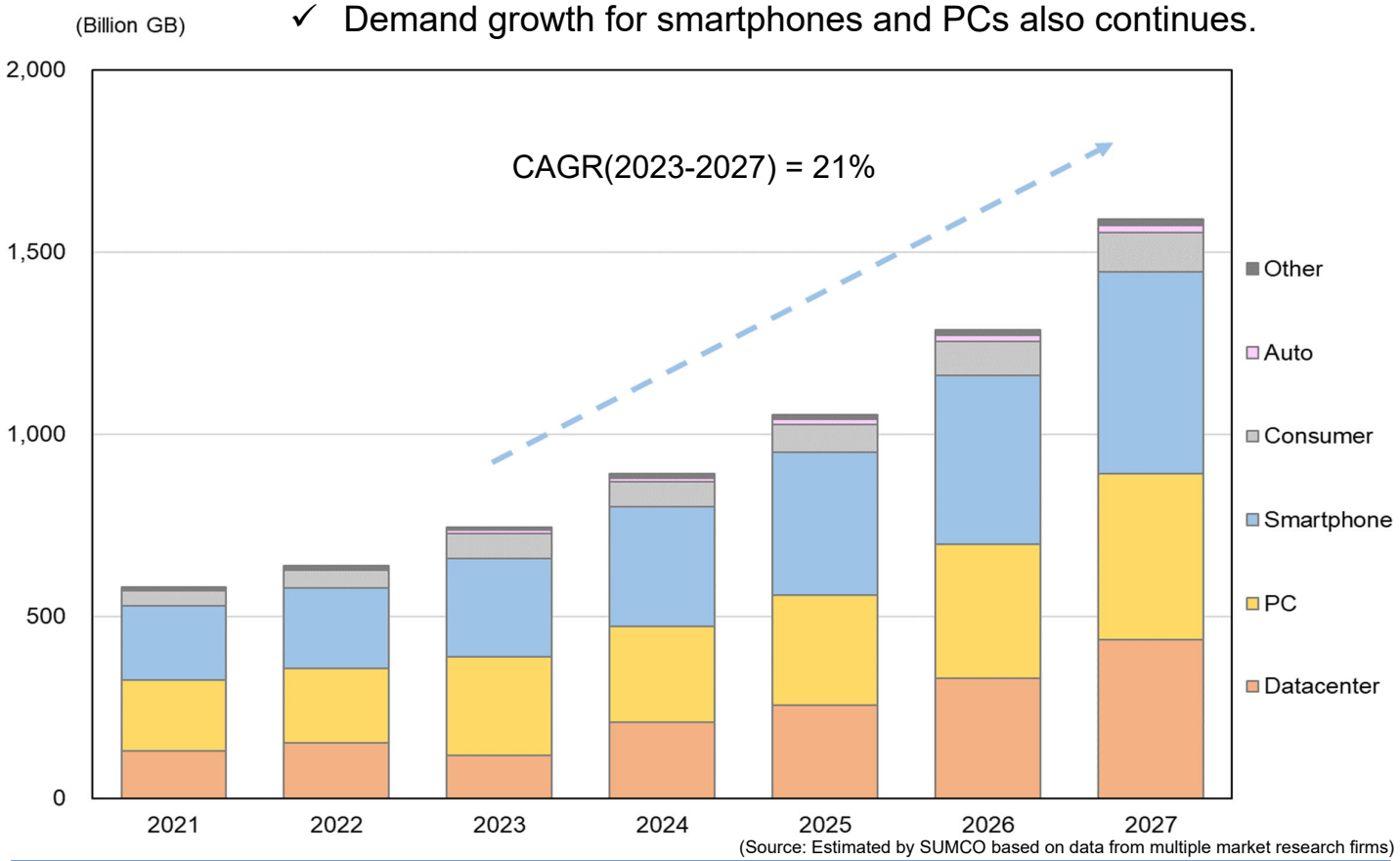
- ✓ Strong demand for wafers for high-end DRAM and HBM continues.
- ✓ Demand growth for wafers for HBM and for DRAM using EUV continues.



(Source: Estimated by SUMCO based on data from multiple market research firms)

3-5. NAND bit demand forecast

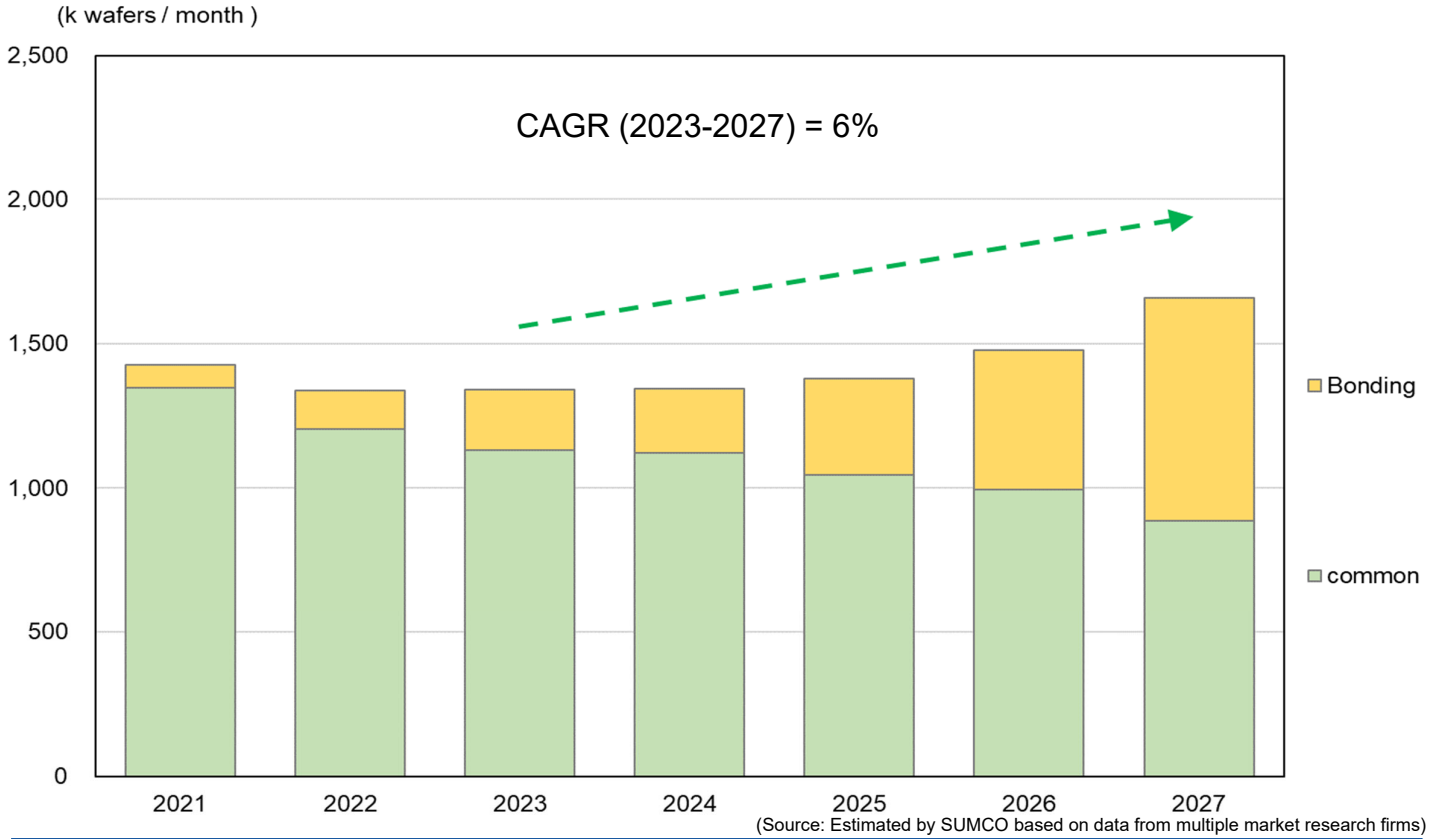
- ✓ Growth rate for data centers is high.
- ✓ Demand growth for smartphones and PCs also continues.



(Source: Estimated by SUMCO based on data from multiple market research firms)

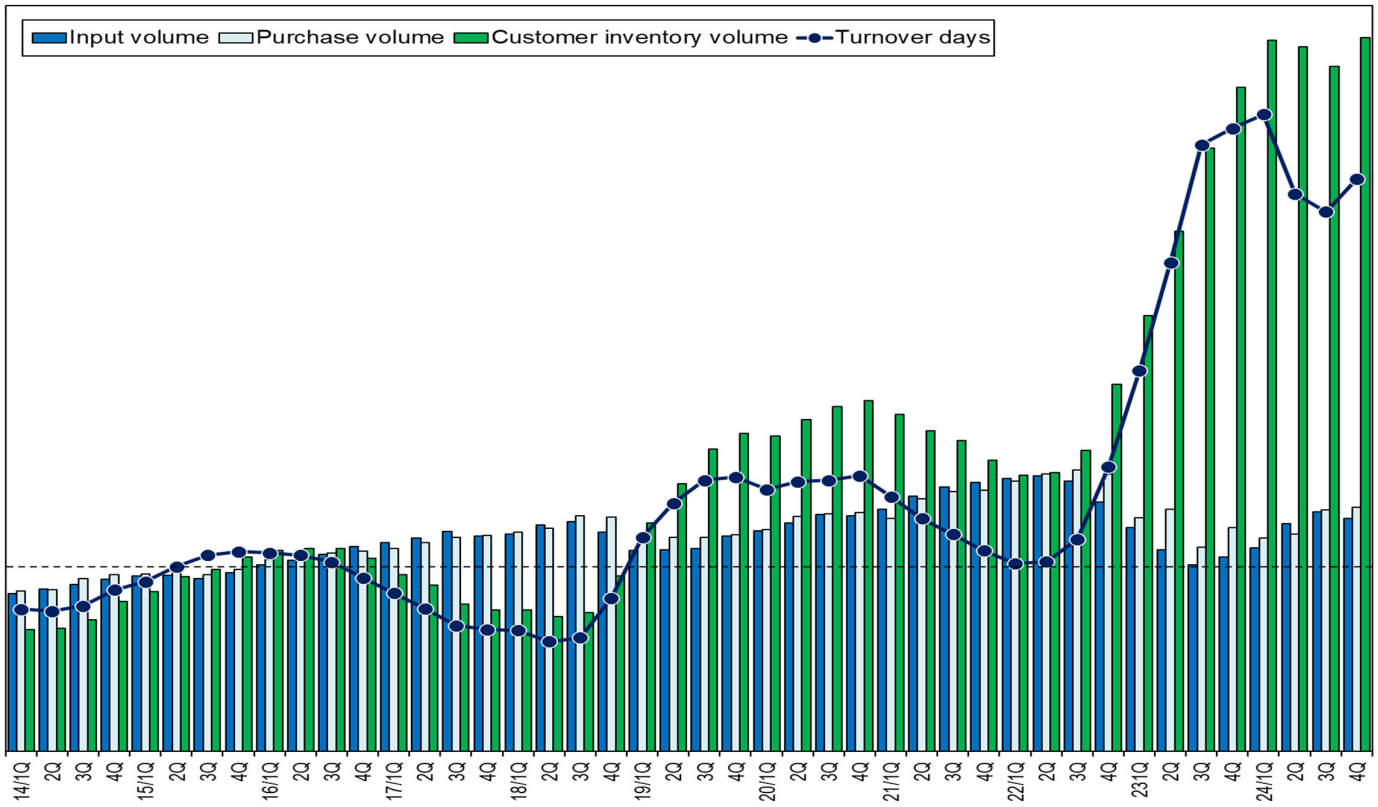
3-6. 300 mm wafer demand forecast for NAND

- ✓ Wafer bonding process is used for high-speed and large-capacity leading-edge NAND.
- ✓ Separately made memory elements and control circuity are bonded to make one NAND chip.



(Source: Estimated by SUMCO based on data from multiple market research firms)

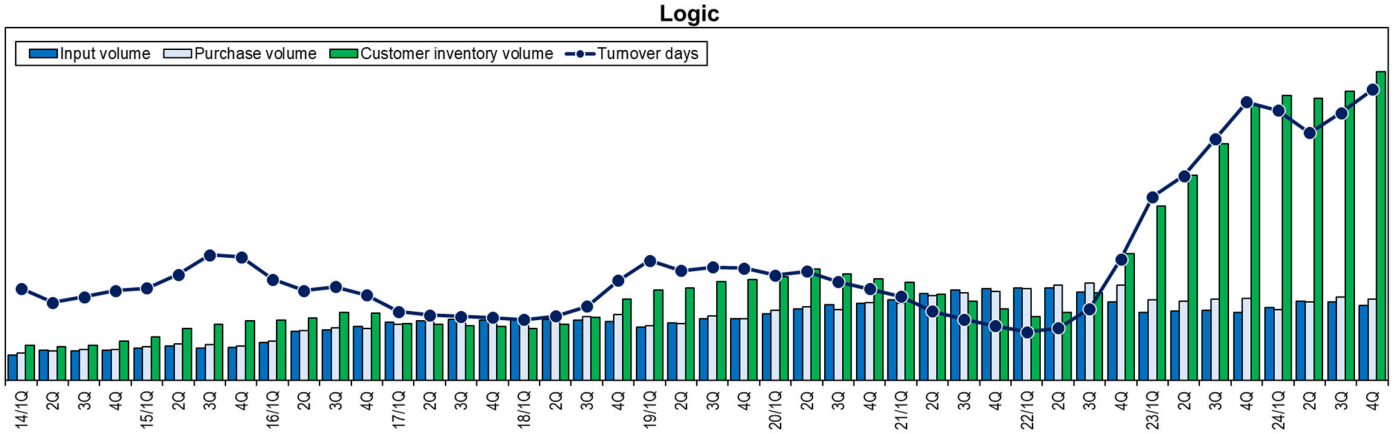
4-1. Customers' 300mm Wafer Inventory Trend



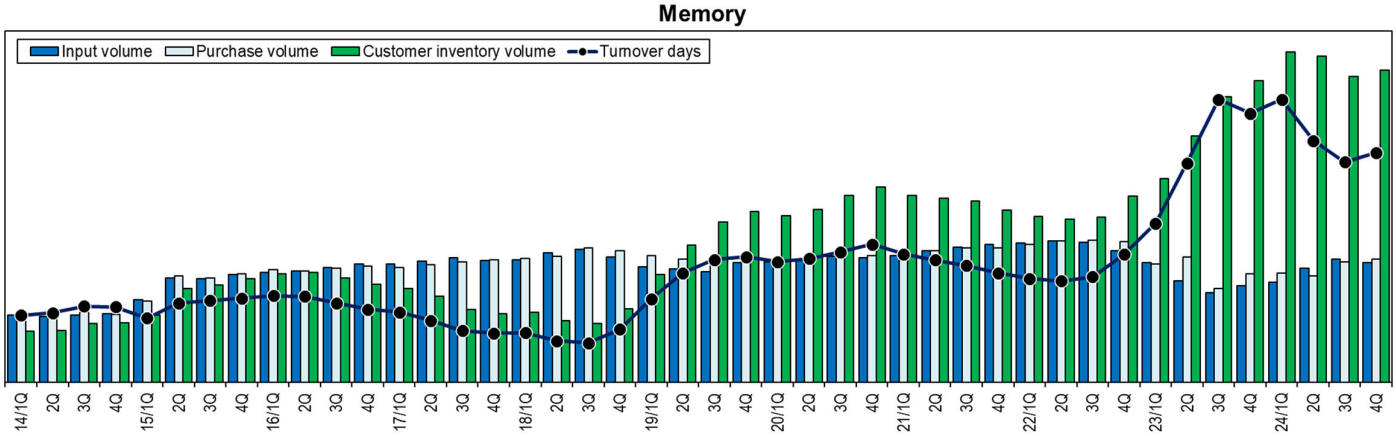
(Source: SUMCO's estimation)

4-2. Customers' 300mm Wafer Inventory (Logic/Memory)

Logic



Memory



(Source: SUMCO's estimation)

FY2024
Consolidated Business Result

Shinichi Kubozoe

Representative Director,
Executive Vice President,
Chief Financial Officer

5-1. Summary of Consolidated Business Result

(Billions of Yen)

	FY2023 Actual	FY2024 Actual 1Q	2Q	3Q	4Q	Total	Change
Net sales	425.9	93.5	104.7	98.4	100.0	396.6	(29.3)
Operating profit	73.0	8.6	12.2	9.1	7.0	36.9	(36.1)
Non-operating income and expenses	(0.4)	0.5	(0.9)	(3.5)	4.4	0.5	+0.9
Ordinary profit	72.6	9.1	11.3	5.6	11.4	37.4	(35.2)
Extraordinary income and losses	20.1	-	-	-	(5.8)	(5.8)	(25.9)
Income taxes	(20.3)	(3.0)	(2.9)	(1.4)	(1.0)	(8.3)	+12.0
Profit attributable to non-controlling interests	(8.6)	(1.1)	(0.8)	(0.6)	(1.0)	(3.5)	+5.1
Profit attributable to owners of parent	63.8	5.0	7.6	3.6	3.6	19.8	(44.0)
Capital expenditure (Acceptance basis)	315.4	76.2	48.5	43.1	47.1	214.9	(100.5)
Depreciation	71.4	17.8	18.1	20.2	22.8	78.9	+7.5
Operating depriciation	71.4	17.4	17.6	19.8	22.3	77.1	+5.7
EBITDA (*1)	144.6	26.1	29.7	29.0	29.2	114.0	(30.6)
Exchange rate (Yen/US$) (*2)	139.8	147.0	155.2	152.6	149.2	151.1	+11.3
Operating margin (%)	17.2%	9.3%	11.6%	9.3%	7.0%	9.3%	(7.8%)
EBITDA margin (%)	34.0%	27.9%	28.4%	29.4%	29.3%	28.8%	(5.2%)
ROE (%)	11.6%	3.2%	5.1%	2.5%	1.9%	3.4%	(8.2%)
Basic Earnings per share (Yen)	182.59	14.46	21.61	10.42	10.34	56.84	(125.75)

*1. EBITDA = Operating profit + Operating Depreciation + Amortization of Goodwill

*2. If the yen appreciates by 1 yen against the US dollar, operating profit of SUMCO will decrease by 1.1 billion yen per year

5-2. Analysis of Changes in Operating Profit

1. 3Q-2024 Actual → 4Q-2024 Actual

(Billions of Yen)

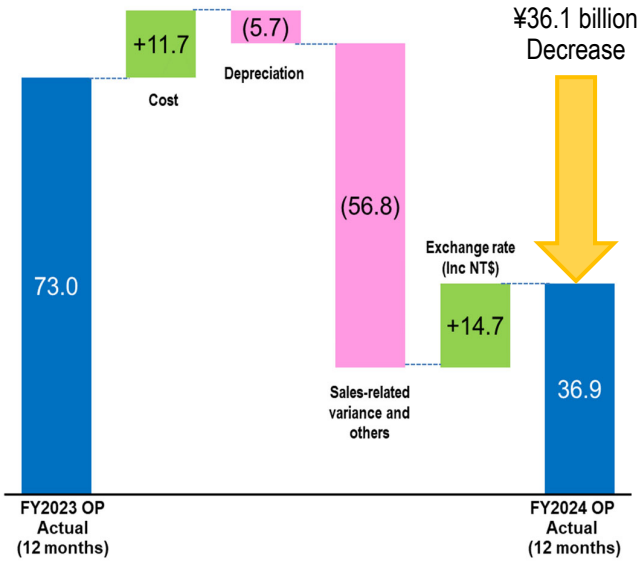
	3Q-2024 Actual	4Q-2024 Actual	Change
Net Sales	98.4	100.0	+1.6
Operating Profit	9.1	7.0	(2.1)
Exchange Rate (Yen/US$)	152.6	149.2	(3.4)



2. FY2023 Actual → FY2024 Actual

(Billions of Yen)

	FY2023 Actual	FY2024 Actual	Change
Net Sales	425.9	396.6	(29.3)
Operating Profit	73.0	36.9	(36.1)
Exchange Rate (Yen/US$)	139.8	151.1	+11.3



5-3. Balance Sheet and Cash-Flow (Consolidated)

1. Consolidated Balance Sheet

(Billions of Yen)

	End of Dec-2023	End of Dec-2024	Change
Cash and deposits	156.3	95.6	(60.7)
Notes and accounts receivable	82.8	92.5	+9.7
Finished goods and WIP	52.0	54.7	+2.7
Raw materials and supplies	166.3	178.5	+12.2
Tangible and intangible assets	559.6	699.6	+140.0
Deferred tax assets	7.3	9.3	+2.0
Other assets	48.7	42.4	(6.3)
Total Assets	1,073.0	1,172.6	+99.6
Interest-bearing debt	224.4	353.9	+129.5
Other liabilities	213.1	161.5	(51.6)
Total Liabilities	437.5	515.4	+77.9
Share capital	199.0	199.0	-
Capital surplus	85.2	85.5	+0.3
Retained earnings	267.7	277.8	+10.1
Non-controlling interests etc.	83.6	94.9	+11.3
Total Net Assets	635.5	657.2	+21.7
Equity-to-asset ratio	53.3%	50.5%	(2.8%)
Net assets per share (Yen)	1,636.2	1,693.2	+57.0
D/E ratio (gross)	0.39x	0.60x	+0.21x
D/E ratio (net)	0.12x	0.44x	+0.32x

2. Consolidated Cash-Flow

(Billions of Yen)

		FY2024 (12months)
	Profit before income taxes	31.6
	Depreciation	78.9
Subtotal		110.5
Decrease (increase) in inventories		(10.4)
Others, net		(30.5)
Net cash provided by operating activities		69.6
Capital expenditure (Acceptance basis)		(214.9)
Others, net		(32.9)
Net cash used in investing activities		(247.8)
Free cash-flow		(178.2)
Cash flow from financing activities, etc.	Dividends paid	(14.6)
	Net proceeds from borrowings	126.0
	Effect of exchange rate change and others	6.1
Net increase (decrease) in cash and cash equivalents		(60.7)

1Q-2025
Consolidated Business Forecast

6-1. 1Q-2025 Consolidated Business Forecast

(Billions of Yen)

	1Q-2024 Actual	4Q-2024 Actual	1Q-2025 Forecast	Chage YoY	Chage QoQ
Net sales	93.5	100.0	102.0	+8.5	+2.0
Operating profit	8.6	7.0	4.5	(4.1)	(2.5)
Non-operating income and expenses	0.5	4.4	(0.5)	(1.0)	(4.9)
Ordinary profit	9.1	11.4	4.0	(5.1)	(7.4)
Extraordinary income and losses	-	(5.8)	-	-	+5.8
Income taxes	(3.0)	(1.0)	(2.2)	+0.8	(1.2)
Profit attributable to non-controlling interests	(1.1)	(1.0)	(0.3)	+0.8	+0.7
Profit attributable to owners of parent	5.0	3.6	1.5	(3.5)	(2.1)
Depreciation	17.8	22.8	24.6	+6.8	+1.8
Operating depriciation	17.4	22.3	24.5	+7.1	+2.2
EBITDA	26.1	29.2	29.0	+2.9	(0.2)
Exchange rate (Yen/US$) (*1)	147.0	149.2	155.0	+8.0	+5.8
Operating margin (%)	9.3%	7.0%	4.4%	(4.9%)	(2.5%)
EBITDA margin (%)	27.9%	29.3%	28.4%	+0.5%	(0.9%)
ROE (%)	3.2%	1.9%	0.9%	(2.2%)	(1.0%)
Basic Earnings per share (Yen)	14.46	10.34	4.29	(10.17)	(6.06)

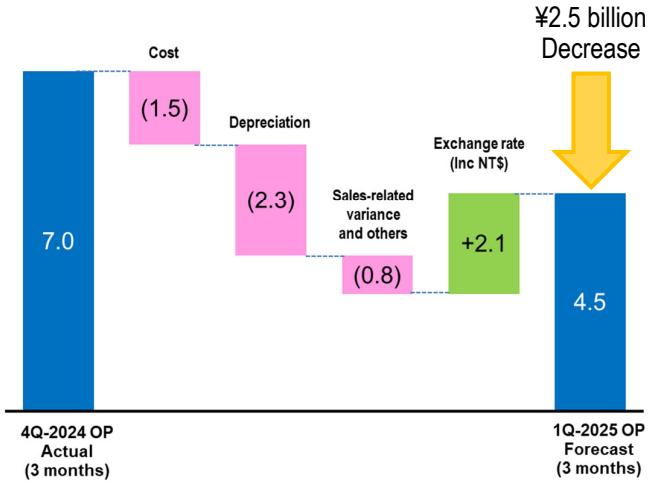
*1 . If the yen appreciates by 1 yen against the US dollar, operating profit of SUMCO will decrease by 1.2 billion yen per year.

6-2. Analysis of Changes in Operating Profit

1. 4Q-2024 Actual → 1Q-2025 Forecast

(Billions of Yen)

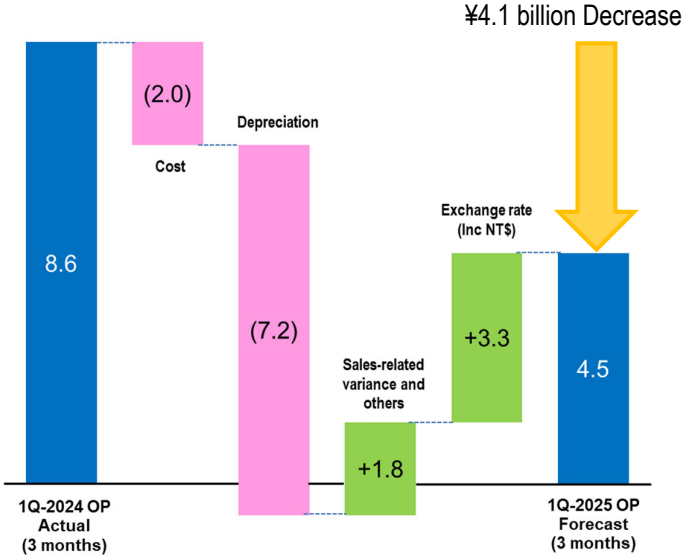
	4Q-2024 Actual	1Q-2025 Forecast	Change
Net Sales	100.0	102.0	+2.0
Operating Profit	7.0	4.5	(2.5)
Exchange Rate (Yen/US$)	149.2	155.0	+5.8



2. 1Q-2024 Actual → 1Q-2025 Forecast

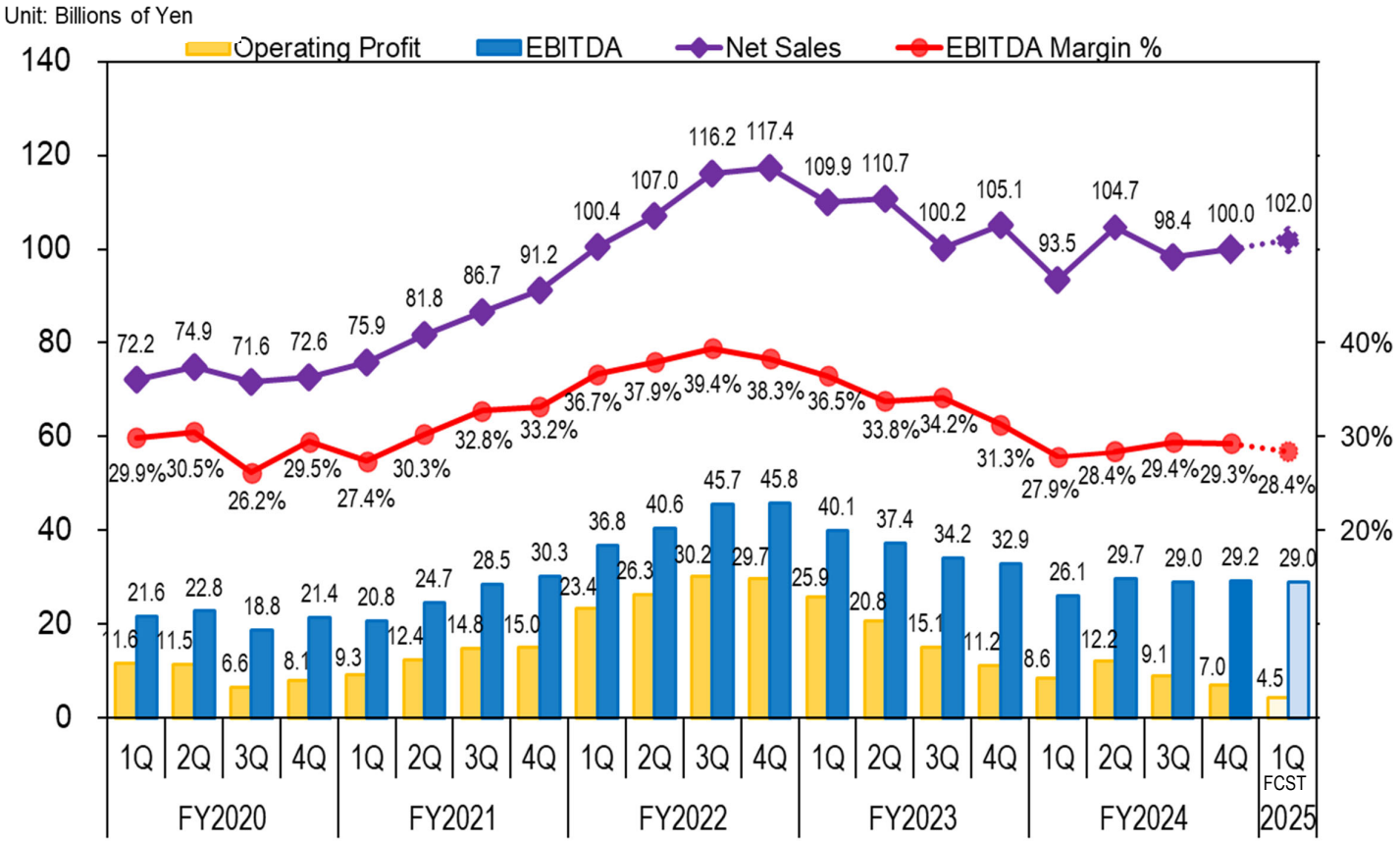
(Billions of Yen)

	1Q-2024 Actual	1Q-2025 Forecast	Change
Net Sales	93.5	102.0	+8.5
Operating Profit	8.6	4.5	(4.1)
Exchange Rate (Yen/US$)	147.0	155.0	+8.0



Reference Materials

Quarterly Trend



URL https://www.sumcosi.com/english/